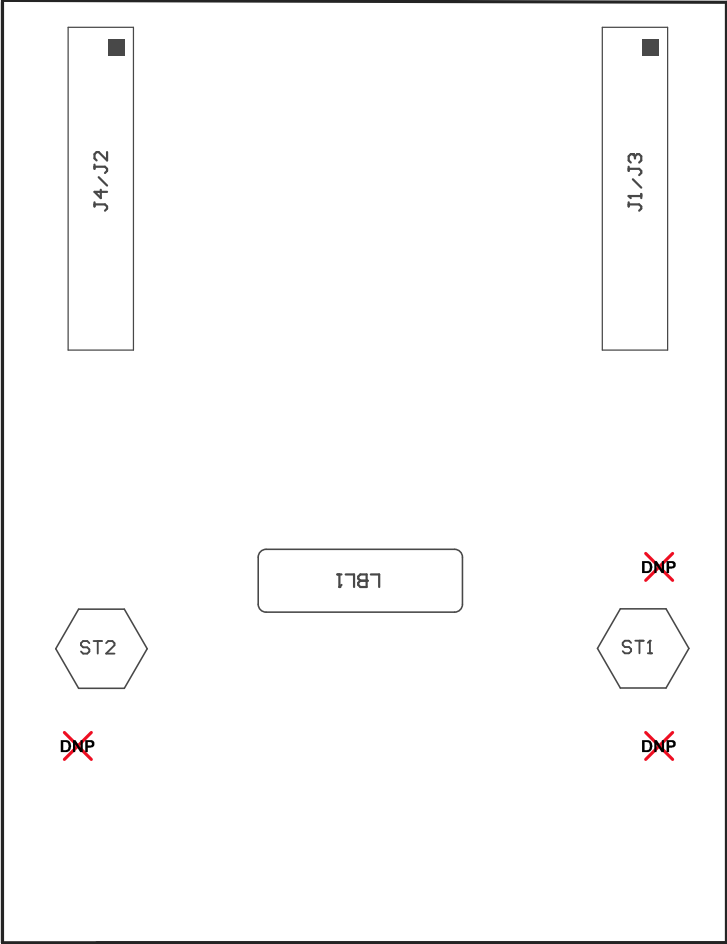


- ZZ1 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
- ZZ2 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean is required.
- ZZ3 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
- ZZ4 ■ Screws SC1 and SC2 are for Standoffs ST1 and ST2

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: .001

PCB VIEWED FROM TOP SIDE	BOARD #: PWR898	REV: A	SUN REV: Not In VersionControl
PLOT NAME = Top Assembly Drawing	GENERATED : 3/15/2017	9:48:06 AM	TEXAS INSTRUMENTS




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